

# **3SK297** Silicon N-Channel Dual Gate MOS FET

REJ03G0816-0300 (Previous ADE-208-389A) Rev.3.00 Aug.10.2005

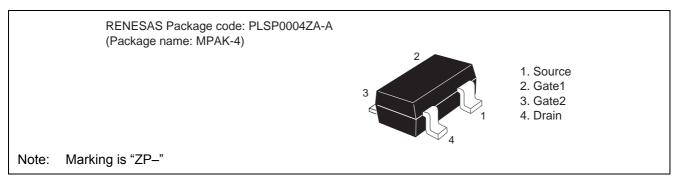
### Application

UHF / VHF RF amplifier

### Features

- Low noise figure. NF = 1.0 dB typ. at f = 200 MHz
- Capable of low voltage operation

### Outline



### Attention:

This device is very sensitive to electro static discharge.

It is recommended to adopt appropriate cautions when handling this transistor.



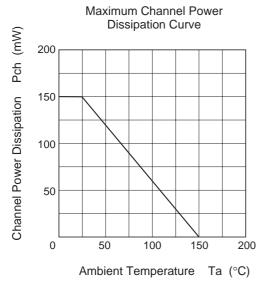
## Absolute Maximum Ratings

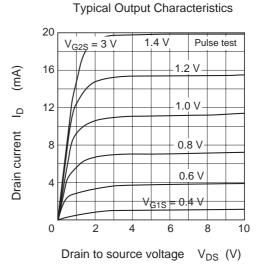
			$(Ta = 25^{\circ}C)$
ltem	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DS</sub>	12	V
Gate 1 to source voltage	V <sub>G1S</sub>	±8	V
Gate 2 to source voltage	V <sub>G2S</sub>	±8	V
Drain current	ID	25	mA
Channel power dissipation	Pch	150	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	۵°

## **Electrical Characteristics**

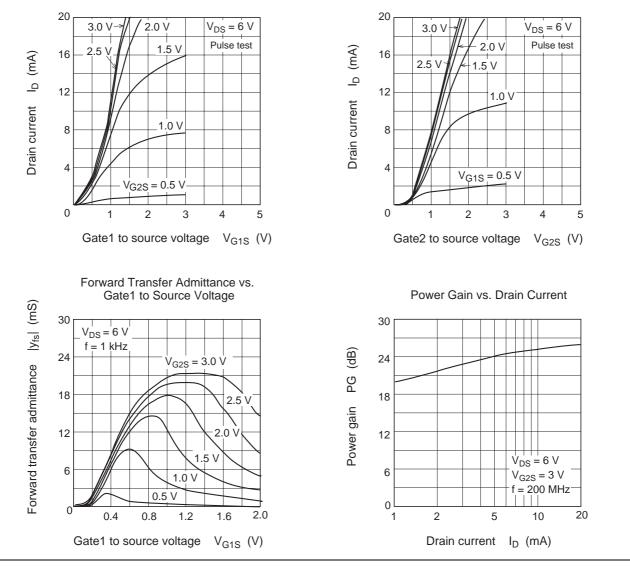
						$(Ta = 25^{\circ}C)$	
Item	Symbol	Min	Тур	Мах	Unit	Test conditions	
Drain to source breakdown voltage	V <sub>(BR)DSX</sub>	12	—		V	$I_D$ = 200 $\mu$ A , $V_{G1S}$ = $-3$ V,	
						$V_{G2S} = -3 V$	
Gate 1 to source breakdown voltage	V <sub>(BR)G1SS</sub>	±8	—	_	V	$I_{G1} = \pm 10 \ \mu A, \ V_{G2S} = V_{DS} = 0$	
Gate 2 to source breakdown voltage	V <sub>(BR) G2SS</sub>	±8	—	_	V	$I_{G2} = \pm 10 \ \mu A, \ V_{G1S} = V_{DS} = 0$	
Gate 1 cutoff current	I <sub>G1SS</sub>	_	—	±100	nA	$V_{G1S} = \pm 6 V, V_{G2S} = V_{DS} = 0$	
Gate 2 cutoff current	I <sub>G2SS</sub>	_	—	±100	nA	$V_{G2S} = \pm 6 V, V_{G1S} = V_{DS} = 0$	
Drain current	I <sub>DS(on)</sub>	0.5	_	10	mA	$V_{DS} = 6 V, V_{G1S} = 0.75 V,$	
						$V_{G2S} = 3 V$	
Gate 1 to source cutoff voltage	V <sub>G1S(off)</sub>	0	—	+1.0	V	$V_{DS}$ = 10 V, $V_{G2S}$ = 3 V,	
						I <sub>D</sub> = 100 μA	
Gate 2 to source cutoff voltage	V <sub>G2S(off)</sub>	0	_	+1.0	V	$V_{DS}$ = 10 V, $V_{G1S}$ = 3 V,	
						I <sub>D</sub> = 100 μA	
Forward transfer admittance	y <sub>fs</sub>	16	20	—	mS	$V_{DS}$ = 6 V, $V_{G2S}$ = 3 V,	
						I <sub>D</sub> = 10 mA, f = 1 kHz	
Input capacitance	Ciss	2.4	2.9	3.4	pF	$V_{DS} = 6 V, V_{G2S} = 3 V,$	
Output capacitance	Coss	0.8	1.0	1.4	pF	I <sub>D</sub> = 10 mA, f = 1 MHz	
Reverse transfer capacitance	Crss	_	0.023	0.04	pF		
Power gain	PG	22	25	_	dB	$V_{DS} = 6 V, V_{G2S} = 3V,$	
Noise figure	NF	_	1.0	1.8	dB	I <sub>D</sub> = 10 mA, f = 200 MHz	
Power gain	PG	12	15	_	dB	$V_{DS} = 6 V, V_{G2S} = 3 V,$	
Noise figure	NF	—	3.2	4.5	dB	I <sub>D</sub> = 10 mA, f = 900 MHz	
Noise figure	NF	—	2.8	3.5	dB	$V_{DS} = 6 V, V_{G2S} = 3 V,$	
						I <sub>D</sub> = 10 mA, f = 60 MHz	

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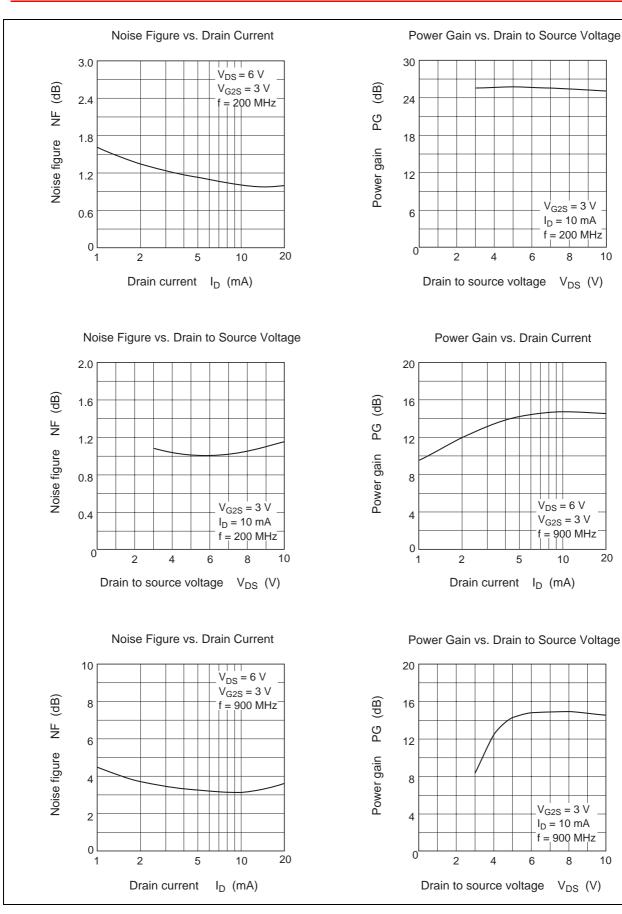
Drain Current vs. Gate2 to Source Voltage



Drain Current vs. Gate1 to Source Voltage

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 $V_{G2S} = 3V$ 

 $I_{\rm D} = 10 \, {\rm mA}$ f = 200 MHz

8

 $V_{DS} = 6 V$ 

 $V_{G2S} = 3 V$ = 900 MHz

10

 $V_{G2S} = 3 V$ 

I<sub>D</sub> = 10 mA f = 900 MHz

8

 $V_{DS}$  (V)

6

10

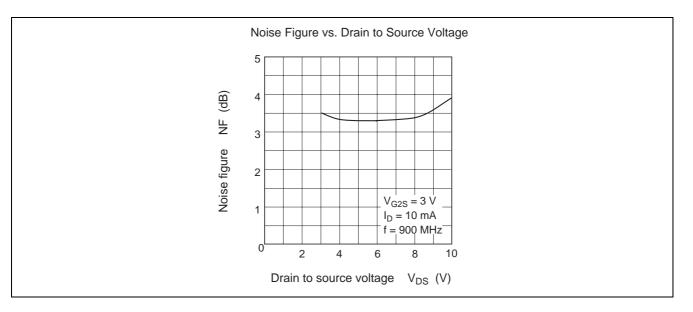
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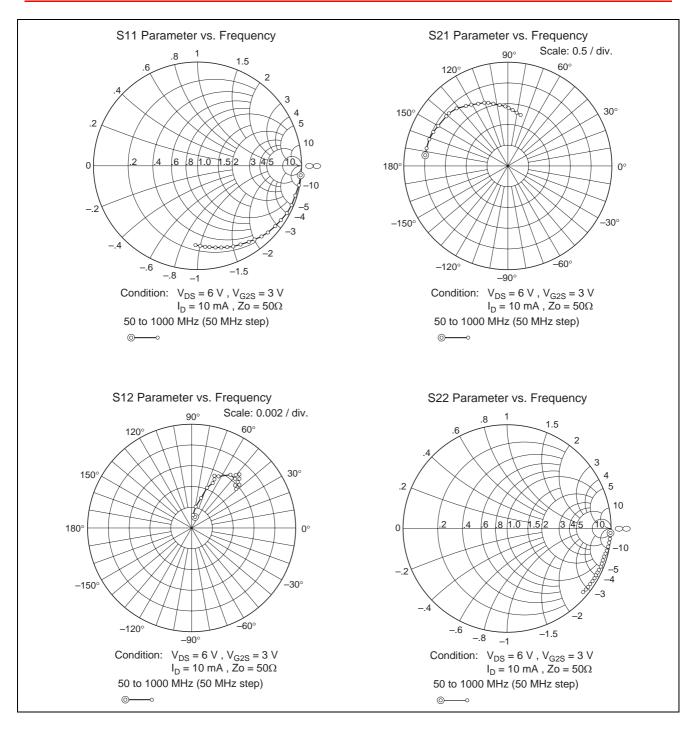
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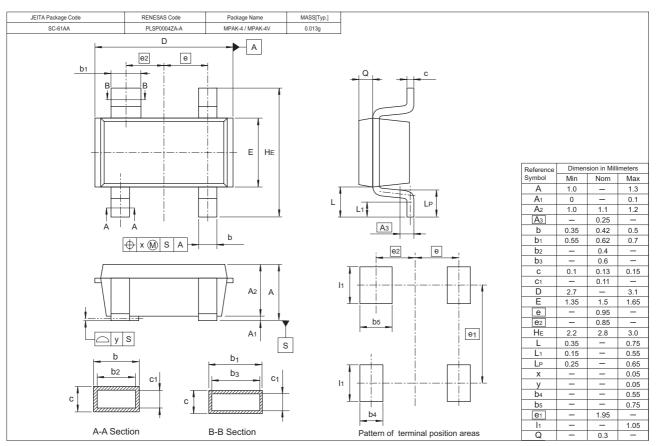
## S Parameter

$(V_{DS} = 6 V,$	$V_{G2S} = 3$	$V, I_D = 10$	$mA, Z_0 =$	50 Ω)
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Freq.	S	11	S21		S	12	\$22		
(MHz)	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	
50	0.994	-5.8	2.04	173.6	0.00116	76.9	0.993	-2.2	
100	0.993	-11.0	2.02	167.4	0.00132	85.7	0.993	-4.5	
150	0.986	-16.8	2.00	161.5	0.00229	78.2	0.991	-6.4	
200	0.980	-22.5	1.98	155.5	0.00313	73.5	0.990	-8.5	
250	0.973	-27.8	1.94	149.6	0.00427	68.7	0.987	-10.5	
300	0.950	-33.0	1.90	142.6	0.00473	63.9	0.985	-12.5	
350	0.936	-38.3	1.86	137.1	0.00536	64.3	0.982	-14.4	
400	0.924	-43.4	1.83	131.6	0.00561	64.5	0.979	-16.2	
450	0.912	-48.0	1.77	126.8	0.00562	60.9	0.975	-18.2	
500	0.893	-52.5	1.71	121.0	0.00640	53.5	0.971	-20.2	
550	0.874	-57.3	1.67	115.5	0.00638	49.3	0.967	-22.0	
600	0.859	-62.0	1.64	111.1	0.00647	49.0	0.964	-23.9	
650	0.846	-66.1	1.58	106.7	0.00667	50.2	0.960	-25.8	
700	0.829	-69.8	1.50	102.1	0.00694	49.3	0.955	-27.6	
750	0.810	-74.2	1.46	97.1	0.00661	46.6	0.952	-29.4	
800	0.802	-78.0	1.44	92.7	0.00618	43.7	0.948	-31.2	
850	0.791	-81.6	1.38	88.9	0.00622	44.7	0.944	-33.2	
900	0.778	-84.6	1.34	84.2	0.00615	43.6	0.940	-35.1	
950	0.756	-88.5	1.30	80.2	0.00576	45.1	0.935	-36.8	
1000	0.751	-92.2	1.26	75.9	0.00562	40.7	0.932	-38.5	



### **Package Dimensions**



### **Ordering Information**

Part Name	Quantity	Shipping Container
3SK297ZP-TL-E	3000	φ 178 mm Reel, 8 mm Emboss Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.



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